

SN74AVCH8T245 8 ビット デュアル電源 バス トランシーバ、 構成可能レベルシフト、電圧変換、3 ステート出力

1 特長

- 制御入力 (DIR および \overline{OE}) の V_{IH} および V_{IL} レベルは V_{CCA} 電圧を基準
- データ入力時のバス ホールドにより、外付けのプルアップまたはプルダウン抵抗が不要
- V_{CC} 絶縁機能
- 完全に構成可能なデュアル レール設計
- 4.6V 許容の I/O
- I_{off} により部分的パワーダウン モードでの動作をサポート
- 最大データレート:
 - 320Mbps ($V_{CCA} \geq 1.8V$ および $V_{CCB} \geq 1.8V$)
 - 170Mbps ($V_{CCA} \leq 1.8V$ または $V_{CCB} \leq 1.8V$)
- JESD 78, Class II 準拠で 100mA 超のラッチアップ性能
- JESD 22 を上回る ESD 保護:
 - 8000V、人体モデル (A114-A)
 - マシン モデルで 200V (A115-A)
 - 1000V、荷電デバイス モデル (C101)

2 アプリケーション

- パーソナル・エレクトロニクス
- 産業用
- エンタープライズ
- テレコミュニケーション

3 概要

SN74AVCH8T245 は、設定可能な 2 本の独立した電源レールを採用した 8 ビット非反転バス トランシーバです。A ポートは V_{CCA} (1.2V~3.6V の任意の電源電圧を入力できます) に追従するように設計されています。同様に B ポートは V_{CCB} (1.2V~3.6V の任意の電源電圧を入力できます) に追従するように設計されています。このため 1.2V、1.5V、1.8V、2.5V、3.3V の任意の電圧ノード間で、低電圧の双方向変換を自在に行うことが可能になります。

SN74AVCH8T245 は、データバス間の非同期通信用に設計されています。このデバイスは、方向制御 (DIR) 入力の論理レベルに応じて、A バスから B バス、または B バスから A バスへデータを転送します。出力イネーブル (\overline{OE}) 入力を使用すると、出力をディセーブルにして、バスを実質的に絶縁できます。

SN74AVCH8T245 の設計では、制御ピン (DIR および \overline{OE}) は V_{CCA} を基準としています。

アクティブなバス ホールド回路により、使用されていない、または駆動されていないピンは、有効なロジック状態に保持されます。プルアップ抵抗またはプルダウン抵抗をバス ホールド回路と組み合わせて使用することは推奨しません。

このデバイスは、 I_{off} を使用する部分的パワーダウン アプリケーション用の動作が完全に規定されています。 I_{off} 回路が出力をディセーブルにするため、デバイスに電流が逆流して損傷に至ることを回避できます。

V_{CC} 絶縁機能により、 V_{CCA} または V_{CCB} のいずれかが GND レベルのとき、出力をハイ インピーダンス状態にできます。電源オン側のバス ホールド回路は常にアクティブのままです。

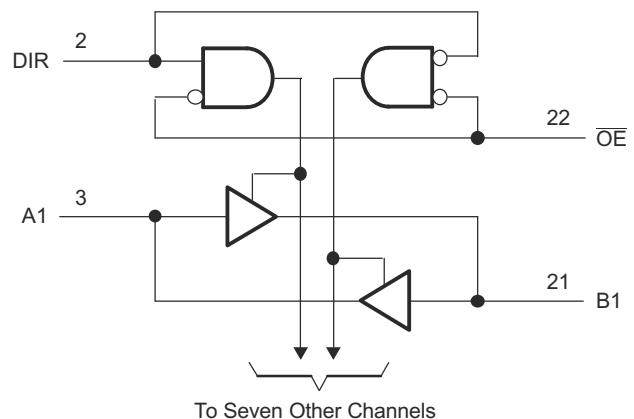
SN74AVCH8T245 ソリューションは単一電源システムと互換性があり、プリント基板の再設計を最小限に抑えながら、後で '245 機能に置き換えることができます。

電源投入時または切断時にデバイスをハイ インピーダンス状態を確保するには、 \overline{OE} をプルダウン抵抗で V_{CCA} につながする必要があります。この抵抗の最小値は、ドライバの電流ソース能力によって決まります。

パッケージ情報

部品番号	パッケージ (1)	パッケージ サイズ(2)
SN74AVCH8T245	DGV (TVSOP, 24)	5 mm × 6.4 mm
	PW (TSSOP, 24)	7.8 mm × 6.4 mm
	RHL (VQFN, 24)	5.5 mm × 3.5 mm

- 詳細については、[セクション 11](#) を参照してください。
- パッケージ サイズ (長さ × 幅) は公称値であり、該当する場合はピンも含まれます。



論理図 (正論理)



Table of Contents

1 特長	1	7.1 Overview.....	17
2 アプリケーション	1	7.2 Functional Block Diagram.....	17
3 概要	1	7.3 Feature Description.....	17
4 Pin Configuration and Functions	3	7.4 Device Functional Modes.....	18
5 Specifications	4	8 Application and Implementation	19
5.1 Absolute Maximum Ratings.....	4	8.1 Application Information.....	19
5.2 ESD Ratings.....	4	8.2 Typical Application.....	19
5.3 Recommended Operating Conditions.....	5	8.3 Power Supply Recommendations.....	20
5.4 Thermal Information.....	6	8.4 Layout.....	21
5.5 Electrical Characteristics.....	6	9 Device and Documentation Support	22
5.6 Switching Characteristics, $V_{CCA} = 1.2V$	8	9.1 Documentation Support.....	22
5.7 Switching Characteristics, $V_{CCA} = 1.5V \pm 0.1V$	9	9.2 ドキュメントの更新通知を受け取る方法.....	22
5.8 Switching Characteristics, $V_{CCA} = 1.8V \pm 0.15V$	10	9.3 サポート・リソース.....	22
5.9 Switching Characteristics, $V_{CCA} = 2.5V \pm 0.2V$	11	9.4 Trademarks.....	22
5.10 Switching Characteristics, $V_{CCA} = 3.3V \pm 0.3V$	12	9.5 静電気放電に関する注意事項.....	22
5.11 Operating Characteristics.....	13	9.6 用語集.....	22
5.12 Typical Characteristics.....	14	10 Revision History	22
6 Parameter Measurement Information	16	11 Mechanical, Packaging, and Orderable Information	23
7 Detailed Description	17		

4 Pin Configuration and Functions

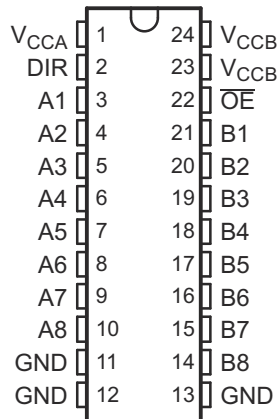


図 4-1. DGV or PW Package, 24-Pin TVSOP or TSSOP (Top View)

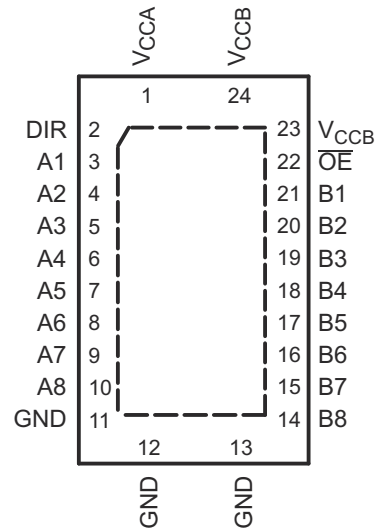


図 4-2. RHL Package, 24-Pin VQFN (Top View)

表 4-1. Pin Functions

PIN		I/O	DESCRIPTION
NAME	NO.		
A1	3	I/O	Input/output A1. Referenced to V _{CCA} .
A2	4	I/O	Input/output A2. Referenced to V _{CCA} .
A3	5	I/O	Input/output A3. Referenced to V _{CCA} .
A4	6	I/O	Input/output A4. Referenced to V _{CCA} .
A5	7	I/O	Input/output A5. Referenced to V _{CCA} .
A6	8	I/O	Input/output A6. Referenced to V _{CCA} .
A7	9	I/O	Input/output A7. Referenced to V _{CCA} .
A8	10	I/O	Input/output A8. Referenced to V _{CCA} .
B1	21	I/O	Input/output B1. Referenced to V _{CCB} .
B2	20	I/O	Input/output B2. Referenced to V _{CCB} .
B3	19	I/O	Input/output B3. Referenced to V _{CCB} .
B4	18	I/O	Input/output B4. Referenced to V _{CCB} .
B5	17	I/O	Input/output B5. Referenced to V _{CCB} .
B6	16	I/O	Input/output B6. Referenced to V _{CCB} .
B7	15	I/O	Input/output B7. Referenced to V _{CCB} .
B8	14	I/O	Input/output B8. Referenced to V _{CCB} .
DIR	2	I	Direction-control signal. Referenced to V _{CCA} .
GND	11, 12, 13	—	Ground
\overline{OE}	22	I	3-state output-mode enables. Pull \overline{OE} high to place all outputs in 3-state mode. Referenced to V _{CCA} .
V _{CCA}	1	—	A-port supply voltage. $1.2V \leq V_{CCA} \leq 3.6V$
V _{CCB}	23, 24	—	B-port supply voltage. $1.2V \leq V_{CCB} \leq 3.6V$

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

			MIN	MAX	UNIT
V _{CCA}	Supply voltage		-0.5	4.6	V
V _{CCB}					
V _I	Input voltage ⁽²⁾	I/O ports (A port)	-0.5	4.6	V
		I/O ports (B port)	-0.5	4.6	
		Control inputs	-0.5	4.6	
V _O	Voltage applied to any output in the high-impedance or power-off state ⁽²⁾	A port	-0.5	4.6	V
		B port	-0.5	4.6	
V _O	Voltage applied to any output in the high or low state ^{(2) (3)}	A port	-0.5	V _{CCA} + 0.5	V
		B port	-0.5	V _{CCB} + 0.5	
I _{IK}	Input clamp current	V _I < 0		-50	mA
I _{OK}	Output clamp current	V _O < 0		-50	mA
I _O	Continuous output current			±50	mA
	Continuous current through V _{CCA} , V _{CCB} , or GND			±100	mA
T _J	Junction temperature		-40	150	°C
T _{stg}	Storage temperature		-65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input voltage and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The output positive-voltage rating may be exceeded up to 4.6V maximum if the output current rating is observed.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

5.2 ESD Ratings

			VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±8000	V
		Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾	±1000	
		Machine model (MM)	±200	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

5.3 Recommended Operating Conditions

See (1) (2)

				MIN	MAX	UNIT
V _{CCA}	Supply voltage			1.2	3.6	V
V _{CCB}	Supply voltage			1.2	3.6	V
V _{IH}	High-level input voltage ⁽¹⁾	Data inputs	V _{CCI} = 1.2V to 1.95V	V _{CCI} × 0.65		V
			V _{CCI} = 1.95V to 2.7V	1.6		
			V _{CCI} = 2.7V to 3.6V	2		
V _{IL}	Low-level input voltage ⁽¹⁾	Data inputs	V _{CCI} = 1.2V to 1.95V	V _{CCI} × 0.35		V
			V _{CCI} = 1.95V to 2.7V	0.7		
			V _{CCI} = 2.7V to 3.6V	0.8		
V _{IH}	High-level input voltage	DIR and \overline{OE} (referenced to V _{CCA})	V _{CCI} = 1.2V to 1.95V	V _{CCA} × 0.65		V
			V _{CCI} = 1.95V to 2.7V	1.6		
			V _{CCI} = 2.7V to 3.6V	2		
V _{IL}	Low-level input voltage	DIR and \overline{OE} (referenced to V _{CCA})	V _{CCI} = 1.2V to 1.95V	V _{CCA} × 0.35		V
			V _{CCI} = 1.95V to 2.7V	0.7		
			V _{CCI} = 2.7V to 3.6V	0.8		
V _I	Input voltage	Control Inputs		0	3.6	V
V _O	Output voltage ⁽²⁾	Active state		0	V _{CCO}	V
		3-state		0	3.6	
I _{OH}	High-level output current	V _{CCO} = 1.2V		-3		mA
		V _{CCO} = 1.4V to 1.6V		-6		
		V _{CCO} = 1.65V to 1.95V		-8		
		V _{CCO} = 2.3V to 2.7V		-9		
		V _{CCO} = 3V to 3.6V		-12		
I _{OL}	Low-level output current	V _{CCO} = 1.2V		3		mA
		V _{CCO} = 1.4V to 1.6V		6		
		V _{CCO} = 1.65V to 1.95V		8		
		V _{CCO} = 2.3V to 2.7V		9		
		V _{CCO} = 3V to 3.6V		12		
$\Delta t/\Delta v$	Input transition rise or fall rate				5	ns/V
T _A	Operating free-air temperature			-40	85	°C

 (1) V_{CCI} is the V_{CC} associated with the input port.

 (2) V_{CCO} is the V_{CC} associated with the output port.

5.4 Thermal Information

THERMAL METRIC ⁽¹⁾		SN74AVCH8T245			UNIT
		DGV (TVSOP)	PW (TSSOP)	RHL (VQFN)	
		24 PINS	24 PINS	24 PINS	
R _{θJA}	Junction-to-ambient thermal resistance ⁽⁴⁾	116.7	93.1	36.8	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	48.5	36.7	32.5	°C/W
R _{θJB}	Junction-to-board thermal resistance	62.1	48.4	15.7	°C/W
ψ _{JT}	Junction-to-top characterization parameter	7.0	93.1	0.7	°C/W
ψ _{JB}	Junction-to-board characterization parameter	61.6	48.0	15.6	°C/W
R _{θJC(bot)}	Junction-to-case (bottom) thermal resistance	N/A	N/A	5.6	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, [SPRA953](#).

5.5 Electrical Characteristics

All typical limits apply over T_A = 25°C, and all maximum and minimum limits apply over T_A = –40°C to 85°C (unless otherwise noted)

PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT	
V _{OH}	High-level output voltage ⁽¹⁾	I _{OH} = –100μA, V _I = V _{IH}	V _{CCA} = V _{CCB} = 1.2V to 3.6V	V _{CCO} – 0.2		V	
		I _{OH} = –3mA, V _I = V _{IH}	V _{CCA} = V _{CCB} = 1.2V		0.95		
		I _{OH} = –6mA, V _I = V _{IH}	V _{CCA} = V _{CCB} = 1.4V	1.05			
		I _{OH} = –8mA, V _I = V _{IH}	V _{CCA} = V _{CCB} = 1.65V	1.2			
		I _{OH} = –9mA, V _I = V _{IH}	V _{CCA} = V _{CCB} = 2.3V	1.75			
		I _{OH} = –12mA, V _I = V _{IH}	V _{CCA} = V _{CCB} = 3V	2.3			
V _{OL}	Low-level output voltage	I _{OL} = 100μA, V _I = V _{IL}	V _{CCA} = V _{CCB} = 1.2V to 3.6V		0.2	V	
		I _{OL} = 3mA, V _I = V _{IL}	V _{CCA} = V _{CCB} = 1.2V		0.15		
		I _{OL} = 6mA, V _I = V _{IL}	V _{CCA} = V _{CCB} = 1.4V		0.35		
		I _{OL} = 8mA, V _I = V _{IL}	V _{CCA} = V _{CCB} = 1.65V		0.45		
		I _{OL} = 9mA, V _I = V _{IL}	V _{CCA} = V _{CCB} = 2.3V		0.55		
		I _{OL} = 12mA, V _I = V _{IL}	V _{CCA} = V _{CCB} = 3V		0.7		
I _I	Control inputs	V _I = V _{CCA} or GND	V _{CCA} = V _{CCB} = 1.2V to 3.6V		±0.025	±1	μA
I _{BHL}	Bus-hold low sustaining current ⁽⁵⁾	V _I = 0.42V	V _{CCA} = V _{CCB} = 1.2V		25	μA	
		V _I = 0.49V	V _{CCA} = V _{CCB} = 1.4V	15			
		V _I = 0.58V	V _{CCA} = V _{CCB} = 1.65V	25			
		V _I = 0.7V	V _{CCA} = V _{CCB} = 2.3V	45			
		V _I = 0.8V	V _{CCA} = V _{CCB} = 3.3V	100			
I _{BHH}	Bus-hold high sustaining current ⁽⁶⁾	V _I = 0.78V	V _{CCA} = V _{CCB} = 1.2V		–25	μA	
		V _I = 0.91V	V _{CCA} = V _{CCB} = 1.4V	–15			
		V _I = 1.07V	V _{CCA} = V _{CCB} = 1.65V	–25			
		V _I = 1.6V	V _{CCA} = V _{CCB} = 2.3V	–45			
		V _I = 2V	V _{CCA} = V _{CCB} = 3.3V	–100			
I _{BHLO}	Bus-hold low overdrive current ⁽³⁾	V _I = 0 to V _{CC}	V _{CCA} = V _{CCB} = 1.2V		50	μA	
			V _{CCA} = V _{CCB} = 1.6V		125		
			V _{CCA} = V _{CCB} = 1.95V		200		
			V _{CCA} = V _{CCB} = 2.7V		300		
			V _{CCA} = V _{CCB} = 3.6V		500		

5.5 Electrical Characteristics (続き)

All typical limits apply over $T_A = 25^\circ\text{C}$, and all maximum and minimum limits apply over $T_A = -40^\circ\text{C}$ to 85°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT	
I_{BHHO}	Bus-hold high overdrive current ⁽⁴⁾	$V_I = 0$ to V_{CC}	$V_{CCA} = V_{CCB} = 1.2\text{V}$			-50	μA	
			$V_{CCA} = V_{CCB} = 1.6\text{V}$		-125			
			$V_{CCA} = V_{CCB} = 1.95\text{V}$		-200			
			$V_{CCA} = V_{CCB} = 2.7\text{V}$		-300			
			$V_{CCA} = V_{CCB} = 3.6\text{V}$		-500			
I_{off}	Input/output power-off leakage current	$V_I = 0\text{V}$ to 3.6V , $V_O = 0\text{V}$ to 3.6V	$V_{CCA} = 0\text{V}$, $V_{CCB} = 0\text{V}$ to 3.6V	A Port	± 0.1	± 5	μA	
			$V_{CCA} = 0\text{V}$ to 3.6V , $V_{CCB} = 0\text{V}$	B Port	± 0.1	± 5		
I_{OZ}	Off-state output current ⁽¹⁾ ⁽²⁾ ⁽⁷⁾	$V_O = V_{CCO}$ or GND, $V_I = V_{CCI}$ or GND, $\overline{OE} = V_{IH}$	$V_{CCA} = V_{CCB} = 3.6\text{V}$	A Port, B Port	± 0.5	± 5	μA	
			$V_{CCA} = 0\text{V}$, $V_{CCB} = 3.6\text{V}$	B Port		± 5		
			$V_{CCA} = 3.6\text{V}$, $V_{CCB} = 0\text{V}$	A Port		± 5		
I_{CCA}	Supply current A port ⁽²⁾	$V_I = V_{CCI}$ or GND, $I_O = 0$	$V_{CCA} = V_{CCB} = 1.2\text{V}$ to 3.6V			8	μA	
			$V_{CCA} = 0\text{V}$, $V_{CCB} = 3.6\text{V}$			-2		
			$V_{CCA} = 3.6\text{V}$, $V_{CCB} = 0\text{V}$			8		
I_{CCB}	Supply current B port ⁽²⁾	$V_I = V_{CCI}$ or GND, $I_O = 0$	$V_{CCA} = V_{CCB} = 1.2\text{V}$ to 3.6V			8	μA	
			$V_{CCA} = 0\text{V}$, $V_{CCB} = 3.6\text{V}$			8		
			$V_{CCA} = 3.6\text{V}$, $V_{CCB} = 0\text{V}$			-2		
$I_{CCA} + I_{CCB}$	Combined supply current ⁽²⁾	$V_I = V_{CCI}$ or GND, $I_O = 0$	$V_{CCA} = V_{CCB} = 1.2\text{V}$ to 3.6V			16	μA	
C_i	Input capacitance control pins	$V_I = 3.3\text{V}$ or GND	$V_{CCA} = V_{CCB} = 3.3\text{V}$			3.5	4.5	pF
C_{io}	Input/output capacitance a or b port	$V_O = 3.3\text{V}$ or GND	$V_{CCA} = V_{CCB} = 3.3\text{V}$			6	7	pF

- (1) V_{CCO} is the V_{CC} associated with the output port.
- (2) V_{CCI} is the V_{CC} associated with the input port.
- (3) An external driver must source at least I_{BHLO} to switch this node from low to high.
- (4) An external driver must sink at least I_{BHHO} to switch this node from high to low.
- (5) The bus-hold circuit can sink at least the minimum low sustaining current at V_{IL} max. I_{BHL} should be measured after lowering V_{IN} to GND and then raising it to V_{IL} max.
- (6) The bus-hold circuit can source at least the minimum high sustaining current at V_{IH} min. I_{BHH} should be measured after raising V_{IN} to V_{CC} and then lowering it to V_{IH} min.
- (7) For I/O ports, the parameter I_{OZ} includes the input leakage current.

5.6 Switching Characteristics, $V_{CCA} = 1.2V$

$T_A = 25^\circ C$ (see [Figure 6-1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH} , t_{PHL}	A	B	$V_{CCB} = 1.2V$		3.1		ns
			$V_{CCB} = 1.5V$		2.6		
			$V_{CCB} = 1.8V$		2.5		
			$V_{CCB} = 2.5V$		3		
			$V_{CCB} = 3.3V$		3.5		
t_{PLH} , t_{PHL}	B	A	$V_{CCB} = 1.2V$		3.1		ns
			$V_{CCB} = 1.5V$		2.7		
			$V_{CCB} = 1.8V$		2.5		
			$V_{CCB} = 2.5V$		2.4		
			$V_{CCB} = 3.3V$		2.3		
t_{PZH} , t_{PZL}	\overline{OE}	A	$V_{CCB} = 1.2V$		5.3		ns
			$V_{CCB} = 1.5V$		5.3		
			$V_{CCB} = 1.8V$		5.3		
			$V_{CCB} = 2.5V$		5.3		
			$V_{CCB} = 3.3V$		5.3		
t_{PZH} , t_{PZL}	\overline{OE}	B	$V_{CCB} = 1.2V$		5.1		ns
			$V_{CCB} = 1.5V$		4		
			$V_{CCB} = 1.8V$		3.5		
			$V_{CCB} = 2.5V$		3.2		
			$V_{CCB} = 3.3V$		3.1		
t_{PHZ} , t_{PLZ}	\overline{OE}	A	$V_{CCB} = 1.2V$		4.8		ns
			$V_{CCB} = 1.5V$		4.8		
			$V_{CCB} = 1.8V$		4.8		
			$V_{CCB} = 2.5V$		4.8		
			$V_{CCB} = 3.3V$		4.8		
t_{PHZ} , t_{PLZ}	\overline{OE}	B	$V_{CCB} = 1.2V$		4.7		ns
			$V_{CCB} = 1.5V$		4		
			$V_{CCB} = 1.8V$		4.1		
			$V_{CCB} = 2.5V$		4.3		
			$V_{CCB} = 3.3V$		5.1		

5.7 Switching Characteristics, $V_{CCA} = 1.5V \pm 0.1V$

All typical limits apply over $T_A = 25^\circ C$, and all maximum and minimum limits apply over $T_A = -40^\circ C$ to $85^\circ C$ (unless otherwise noted) (see [Figure 6-1](#))

PARAMETER		FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH} , t_{PHL}	Propagation delay time: low-to-high-level output and high-to-low level output	A	B	$V_{CCB} = 1.2V$		2.7		ns
				$V_{CCB} = 1.5V$	0.5	5.4		
				$V_{CCB} = 1.8V$	0.5	4.6		
				$V_{CCB} = 2.5V$	0.5	4.9		
				$V_{CCB} = 3.3V$	0.5	6.8		
t_{PLH} , t_{PHL}	Propagation delay time: low-to-high-level output and high-to-low level output	B	A	$V_{CCB} = 1.2V$		2.6		ns
				$V_{CCB} = 1.5V$	0.5	5.4		
				$V_{CCB} = 1.8V$	0.5	5.1		
				$V_{CCB} = 2.5V$	0.5	4.7		
				$V_{CCB} = 3.3V$	0.5	4.5		
t_{PZH} , t_{PZL}	Enable time: to high level and to low level	\overline{OE}	A	$V_{CCB} = 1.2V$		3.7		ns
				$V_{CCB} = 1.5V$	1.1	8.7		
				$V_{CCB} = 1.8V$	1.1	8.7		
				$V_{CCB} = 2.5V$	1.1	8.7		
				$V_{CCB} = 3.3V$	1.1	8.7		
t_{PZH} , t_{PZL}	Enable time: to high level and to low level	\overline{OE}	B	$V_{CCB} = 1.2V$		4.8		ns
				$V_{CCB} = 1.5V$	1.1	7.6		
				$V_{CCB} = 1.8V$	1.1	7.1		
				$V_{CCB} = 2.5V$	1.1	5.6		
				$V_{CCB} = 3.3V$	1.1	5.2		
t_{PHZ} , t_{PLZ}	Disable time: from high level and from low level	\overline{OE}	A	$V_{CCB} = 1.2V$		3.1		ns
				$V_{CCB} = 1.5V$	0.5	8.6		
				$V_{CCB} = 1.8V$	0.5	8.6		
				$V_{CCB} = 2.5V$	0.5	8.6		
				$V_{CCB} = 3.3V$	0.5	8.6		
t_{PHZ} , t_{PLZ}	Disable time: from high level and from low level	\overline{OE}	B	$V_{CCB} = 1.2V$		4.1		ns
				$V_{CCB} = 1.5V$	0.5	8.4		
				$V_{CCB} = 1.8V$	0.5	7.6		
				$V_{CCB} = 2.5V$	0.5	7.2		
				$V_{CCB} = 3.3V$	0.5	7.8		

5.8 Switching Characteristics, $V_{CCA} = 1.8V \pm 0.15V$

All typical limits apply over $T_A = 25^\circ C$, and all maximum and minimum limits apply over $T_A = -40^\circ C$ to $85^\circ C$ (unless otherwise noted) (see [Figure 6-1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH} , t_{PHL}	A	B	$V_{CCB} = 1.2V$	2.5		ns	
			$V_{CCB} = 1.5V$	0.5	5.1		
			$V_{CCB} = 1.8V$	0.5	4.4		
			$V_{CCB} = 2.5V$	0.5	4		
			$V_{CCB} = 3.3V$	0.5	3.9		
t_{PLH} , t_{PHL}	B	A	$V_{CCB} = 1.2V$	2.5		ns	
			$V_{CCB} = 1.5V$	0.5	4.6		
			$V_{CCB} = 1.8V$	0.5	4.4		
			$V_{CCB} = 2.5V$	0.5	3.9		
			$V_{CCB} = 3.3V$	0.5	3.7		
t_{PZH} , t_{PZL}	\overline{OE}	A	$V_{CCB} = 1.2V$	3		ns	
			$V_{CCB} = 1.5V$	1	6.8		
			$V_{CCB} = 1.8V$	1	6.8		
			$V_{CCB} = 2.5V$	1	6.8		
			$V_{CCB} = 3.3V$	1	6.8		
t_{PZH} , t_{PZL}	\overline{OE}	B	$V_{CCB} = 1.2V$	4.6		ns	
			$V_{CCB} = 1.5V$	1.1	8.2		
			$V_{CCB} = 1.8V$	1	6.7		
			$V_{CCB} = 2.5V$	0.5	5.1		
			$V_{CCB} = 3.3V$	0.5	4.5		
t_{PHZ} , t_{PLZ}	\overline{OE}	A	$V_{CCB} = 1.2V$	2.8		ns	
			$V_{CCB} = 1.5V$	0.5	7.1		
			$V_{CCB} = 1.8V$	0.5	7.1		
			$V_{CCB} = 2.5V$	0.5	7.1		
			$V_{CCB} = 3.3V$	0.5	7.1		
t_{PHZ} , t_{PLZ}	\overline{OE}	B	$V_{CCB} = 1.2V$	3.9		ns	
			$V_{CCB} = 1.5V$	0.5	7.8		
			$V_{CCB} = 1.8V$	0.5	6.9		
			$V_{CCB} = 2.5V$	0.5	6		
			$V_{CCB} = 3.3V$	0.5	5.8		

5.9 Switching Characteristics, $V_{CCA} = 2.5V \pm 0.2V$

All typical limits apply over $T_A = 25^\circ C$, and all maximum and minimum limits apply over $T_A = -40^\circ C$ to $85^\circ C$ (unless otherwise noted) (see [Figure 6-1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH} , t_{PHL}	A	B	$V_{CCB} = 1.2V$		2.4		ns
			$V_{CCB} = 1.5V$	0.5		4.7	
			$V_{CCB} = 1.8V$	0.5		3.9	
			$V_{CCB} = 2.5V$	0.5		3.1	
			$V_{CCB} = 3.3V$	0.5		2.8	
t_{PLH} , t_{PHL}	B	A	$V_{CCB} = 1.2V$		3		ns
			$V_{CCB} = 1.5V$	0.5		4.9	
			$V_{CCB} = 1.8V$	0.5		4	
			$V_{CCB} = 2.5V$	0.5		3.1	
			$V_{CCB} = 3.3V$	0.5		2.9	
t_{PZH} , t_{PZL}	\overline{OE}	A	$V_{CCB} = 1.2V$		2.2		ns
			$V_{CCB} = 1.5V$	0.5		4.8	
			$V_{CCB} = 1.8V$	0.5		4.8	
			$V_{CCB} = 2.5V$	0.5		4.8	
			$V_{CCB} = 3.3V$	0.5		4.8	
t_{PZH} , t_{PZL}	\overline{OE}	B	$V_{CCB} = 1.2V$		4.5		ns
			$V_{CCB} = 1.5V$	1.1		7.9	
			$V_{CCB} = 1.8V$	0.5		6.4	
			$V_{CCB} = 2.5V$	0.5		4.6	
			$V_{CCB} = 3.3V$	0.5		4	
t_{PHZ} , t_{PLZ}	\overline{OE}	A	$V_{CCB} = 1.2V$		1.8		ns
			$V_{CCB} = 1.5V$	0.5		5.1	
			$V_{CCB} = 1.8V$	0.5		5.1	
			$V_{CCB} = 2.5V$	0.5		5.1	
			$V_{CCB} = 3.3V$	0.5		5.1	
t_{PHZ} , t_{PLZ}	\overline{OE}	B	$V_{CCB} = 1.2V$		3.6		ns
			$V_{CCB} = 1.5V$	0.5		7.1	
			$V_{CCB} = 1.8V$	0.5		6.3	
			$V_{CCB} = 2.5V$	0.5		5.1	
			$V_{CCB} = 3.3V$	0.5		3.9	

5.10 Switching Characteristics, $V_{CCA} = 3.3V \pm 0.3V$

All typical limits apply over $T_A = 25^\circ C$, and all maximum and minimum limits apply over $T_A = -40^\circ C$ to $85^\circ C$ (unless otherwise noted) (see [Figure 6-1](#))

PARAMETER		FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH} , t_{PHL}	Propagation delay time: low-to-high-level output and high-to-low level output	A	B	$V_{CCB} = 1.2V$	2.3		ns	
				$V_{CCB} = 1.5V$	0.5	4.5		
				$V_{CCB} = 1.8V$	0.5	3.7		
				$V_{CCB} = 2.5V$	0.5	2.9		
				$V_{CCB} = 3.3V$	0.5	2.5		
t_{PLH} , t_{PHL}	Propagation delay time: low-to-high-level output and high-to-low level output	B	A	$V_{CCB} = 1.2V$	3.5		ns	
				$V_{CCB} = 1.5V$	0.5	6.8		
				$V_{CCB} = 1.8V$	0.5	3.9		
				$V_{CCB} = 2.5V$	0.5	2.8		
				$V_{CCB} = 3.3V$	0.5	2.5		
t_{PZH} , t_{PZL}	Enable time: to high level and to low level	\overline{OE}	A	$V_{CCB} = 1.2V$	2		ns	
				$V_{CCB} = 1.5V$	0.5	4		
				$V_{CCB} = 1.8V$	0.5	4		
				$V_{CCB} = 2.5V$	0.5	4		
				$V_{CCB} = 3.3V$	0.5	4		
t_{PZH} , t_{PZL}	Enable time: to high level and to low level	\overline{OE}	B	$V_{CCB} = 1.2V$	4.5		ns	
				$V_{CCB} = 1.5V$	1.1	7.8		
				$V_{CCB} = 1.8V$	0.5	6.2		
				$V_{CCB} = 2.5V$	0.5	4.5		
				$V_{CCB} = 3.3V$	0.5	3.9		
t_{PHZ} , t_{PLZ}	Disable time: from high level and from low level	\overline{OE}	A	$V_{CCB} = 1.2V$	1.7		ns	
				$V_{CCB} = 1.5V$	0.5	4		
				$V_{CCB} = 1.8V$	0.5	4		
				$V_{CCB} = 2.5V$	0.5	4		
				$V_{CCB} = 3.3V$	0.5	4		
t_{PHZ} , t_{PLZ}	Disable time: from high level and from low level	\overline{OE}	B	$V_{CCB} = 1.2V$	3.4		ns	
				$V_{CCB} = 1.5V$	0.5	6.9		
				$V_{CCB} = 1.8V$	0.5	6		
				$V_{CCB} = 2.5V$	0.5	4.8		
				$V_{CCB} = 3.3V$	0.5	4.2		

5.11 Operating Characteristics

T_A = 25°C

PARAMETER		FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	TYP	UNIT	
C _{pdA}	Power dissipation capacitance per transceiver ⁽¹⁾ port A - outputs enabled	A	B	C _L = 0pF, f = 10MHz, t _r = t _f = 1ns	V _{CCA} = V _{CCB} = 1.2V	1	pF
					V _{CCA} = V _{CCB} = 1.5V	1	
					V _{CCA} = V _{CCB} = 1.8V	1	
					V _{CCA} = V _{CCB} = 2.5V	1	
					V _{CCA} = V _{CCB} = 3.3V	1	
	Power dissipation capacitance per transceiver ⁽¹⁾ port A - outputs disabled	A	B	C _L = 0pF, f = 10MHz, t _r = t _f = 1ns	V _{CCA} = V _{CCB} = 1.2V	1	
					V _{CCA} = V _{CCB} = 1.5V	1	
					V _{CCA} = V _{CCB} = 1.8V	1	
					V _{CCA} = V _{CCB} = 2.5V	1	
					V _{CCA} = V _{CCB} = 3.3V	1	
	Power dissipation capacitance per transceiver ⁽¹⁾ port A - outputs enabled	B	A	C _L = 0pF, f = 10MHz, t _r = t _f = 1ns	V _{CCA} = V _{CCB} = 1.2V	12	
					V _{CCA} = V _{CCB} = 1.5V	12	
					V _{CCA} = V _{CCB} = 1.8V	12	
					V _{CCA} = V _{CCB} = 2.5V	13	
					V _{CCA} = V _{CCB} = 3.3V	14	
	Power dissipation capacitance per transceiver ⁽¹⁾ port A - outputs disabled	B	A	C _L = 0pF, f = 10MHz, t _r = t _f = 1ns	V _{CCA} = V _{CCB} = 1.2V	1	
V _{CCA} = V _{CCB} = 1.5V					1		
V _{CCA} = V _{CCB} = 1.8V					1		
V _{CCA} = V _{CCB} = 2.5V					1		
V _{CCA} = V _{CCB} = 3.3V					1		
C _{pdB}	Power dissipation capacitance per transceiver ⁽¹⁾ port B - outputs enabled	A	B	C _L = 0pF, f = 10MHz, t _r = t _f = 1ns	V _{CCA} = V _{CCB} = 1.2V	12	pF
					V _{CCA} = V _{CCB} = 1.5V	12	
					V _{CCA} = V _{CCB} = 1.8V	12	
					V _{CCA} = V _{CCB} = 2.5V	13	
					V _{CCA} = V _{CCB} = 3.3V	14	
	Power dissipation capacitance per transceiver ⁽¹⁾ port B - outputs disabled	A	B	C _L = 0pF, f = 10MHz, t _r = t _f = 1ns	V _{CCA} = V _{CCB} = 1.2V	1	
					V _{CCA} = V _{CCB} = 1.5V	1	
					V _{CCA} = V _{CCB} = 1.8V	1	
					V _{CCA} = V _{CCB} = 2.5V	1	
					V _{CCA} = V _{CCB} = 3.3V	1	
	Power dissipation capacitance per transceiver ⁽¹⁾ port B - outputs enabled	B	A	C _L = 0pF, f = 10MHz, t _r = t _f = 1ns	V _{CCA} = V _{CCB} = 1.2V	1	
					V _{CCA} = V _{CCB} = 1.5V	1	
					V _{CCA} = V _{CCB} = 1.8V	1	
					V _{CCA} = V _{CCB} = 2.5V	1	
					V _{CCA} = V _{CCB} = 3.3V	1	
	Power dissipation capacitance per transceiver ⁽¹⁾ port B - outputs disabled	B	A	C _L = 0pF, f = 10MHz, t _r = t _f = 1ns	V _{CCA} = V _{CCB} = 1.2V	1	
V _{CCA} = V _{CCB} = 1.5V					1		
V _{CCA} = V _{CCB} = 1.8V					1		
V _{CCA} = V _{CCB} = 2.5V					1		
V _{CCA} = V _{CCB} = 3.3V					1		

(1) See to TI application report, *CMOS Power Consumption and Cpd Calculation* (SCAA035).

5.12 Typical Characteristics

T_A = 25°C

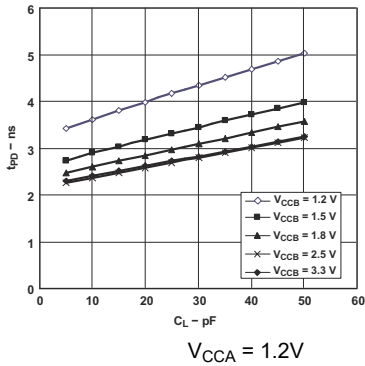


图 5-1. Typical Propagation Delay (A to B) vs Load Capacitance

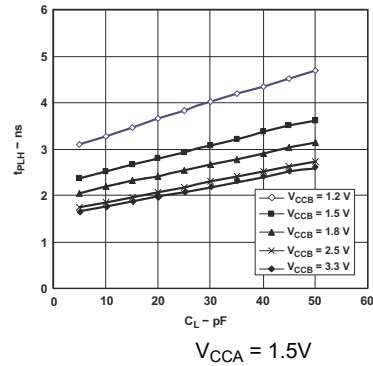


图 5-2. Typical Propagation Delay (A to B) vs Load Capacitance

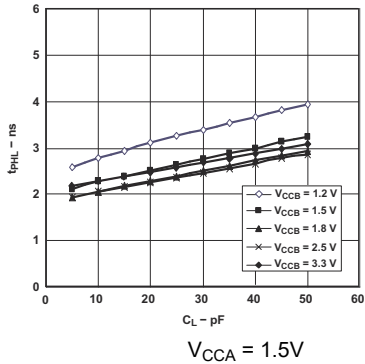


图 5-3. Typical Propagation Delay (A to B) vs Load Capacitance

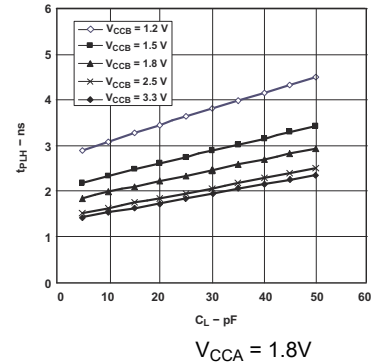


图 5-4. Typical Propagation Delay (A to B) vs Load Capacitance

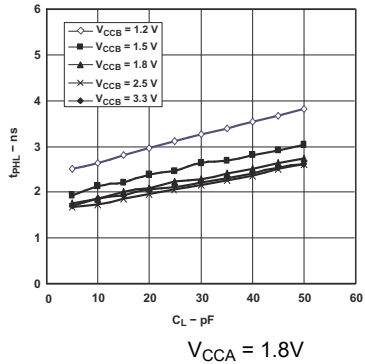


图 5-5. Typical Propagation Delay (A to B) vs Load Capacitance

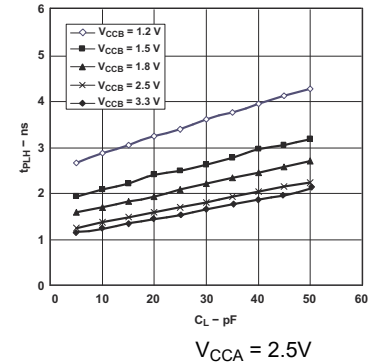


图 5-6. Typical Propagation Delay (A to B) vs Load Capacitance

5.12 Typical Characteristics (continued)

T_A = 25°C

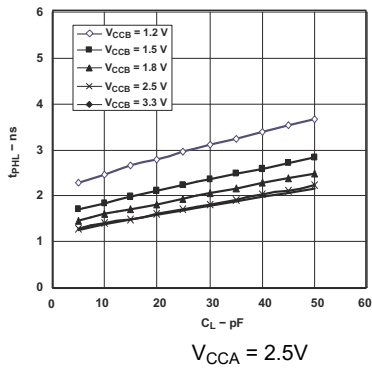


Figure 5-7. Typical Propagation Delay (A to B) vs Load Capacitance

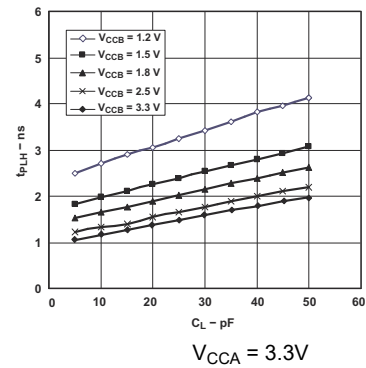


Figure 5-8. Typical Propagation Delay (A to B) vs Load Capacitance

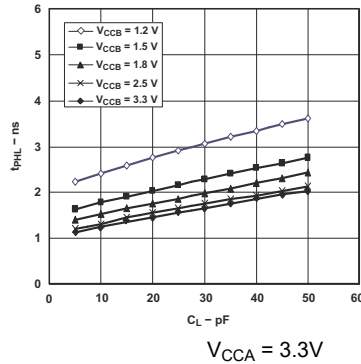
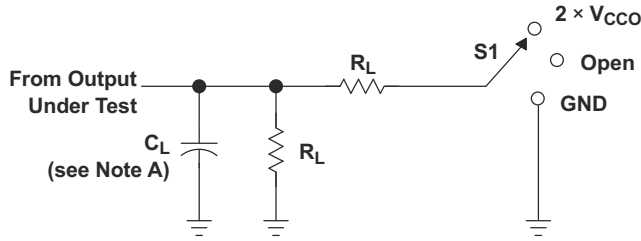


Figure 5-9. Typical Propagation Delay (A to B) vs Load Capacitance

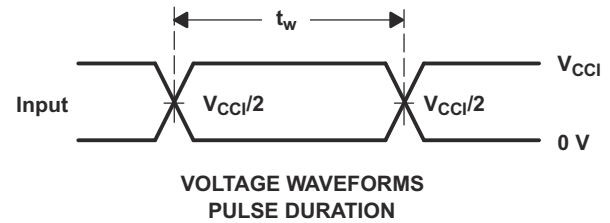
6 Parameter Measurement Information



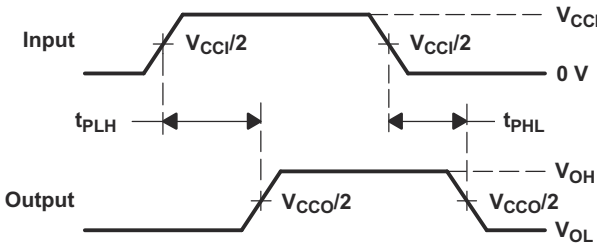
LOAD CIRCUIT

TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	$2 \times V_{CCO}$
t_{PHZ}/t_{PZH}	GND

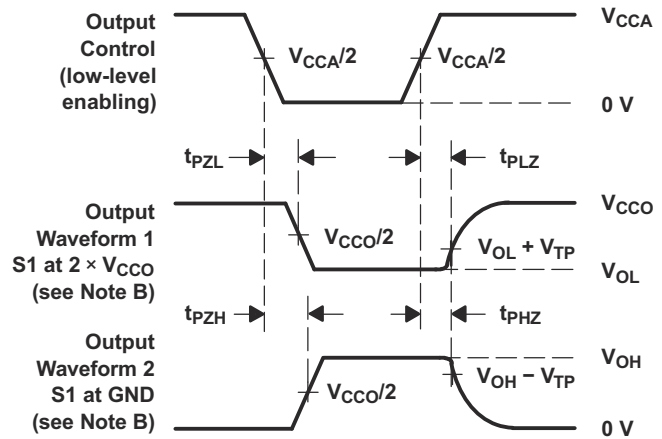
V_{CCO}	C_L	R_L	V_{TP}
1.2 V	15 pF	2 k Ω	0.1 V
1.5 V \pm 0.1 V	15 pF	2 k Ω	0.1 V
1.8 V \pm 0.15 V	15 pF	2 k Ω	0.15 V
2.5 V \pm 0.2 V	15 pF	2 k Ω	0.15 V
3.3 V \pm 0.3 V	15 pF	2 k Ω	0.3 V



VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50 \Omega$, $dv/dt \geq 1$ V/ns.
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .
 - H. V_{CC1} is the V_{CC} associated with the input port.
 - I. V_{CCO} is the V_{CC} associated with the output port.

图 6-1. Load Circuit and Voltage Waveforms

7.3.4 Bus-Hold Circuitry

Active bus-hold circuitry holds unused or undriven data inputs at a valid logic state, which helps with board space savings and reduced component costs. Use of pull-up or pull-down resistors with the bus-hold circuitry is not recommended. For more information, see [Bus-Hold Circuit](#).

7.3.5 V_{CC} Isolation Feature

The V_{CC} isolation feature allows both ports to be in a high-impedance state if either V_{CCA} or V_{CCB} are at GND (or < 0.4V). For more information, see I_{OZ} in the [Electrical Characteristics](#). This feature prevents false logic levels from being presented to either bus.

7.4 Device Functional Modes

表 7-2 lists the functional modes of the SN74AVCH8T245.

表 7-2. Function Table (Each 8-Bit Section)

CONTROL INPUTS ⁽¹⁾		OUTPUT CIRCUITS		OPERATION
OE	DIR	A PORT	B PORT	
L	L	Enabled	Hi-Z	B data to A bus
L	H	Hi-Z	Enabled	A data to B bus
H	X	Hi-Z	Hi-Z	Isolation

(1) Input circuits of the data I/Os are always active.

8 Application and Implementation

注

以下のアプリケーション情報は、TI の製品仕様に含まれるものではなく、TI ではその正確性または完全性を保証いたしません。個々の目的に対する製品の適合性については、お客様の責任で判断していただくこととなります。お客様は自身の設計実装を検証しテストすることで、システムの機能を確認する必要があります。

8.1 Application Information

The SN74AVCH8T245 device can be used in level-translation applications for interfacing devices or systems operating at different interface voltages with one another. The SN74AVCH8T245 device is an excellent choice for data transmission when direction is different. The maximum data rate can be up to 320Mbps when device voltage power supply is more than 1.8V.

8.2 Typical Application

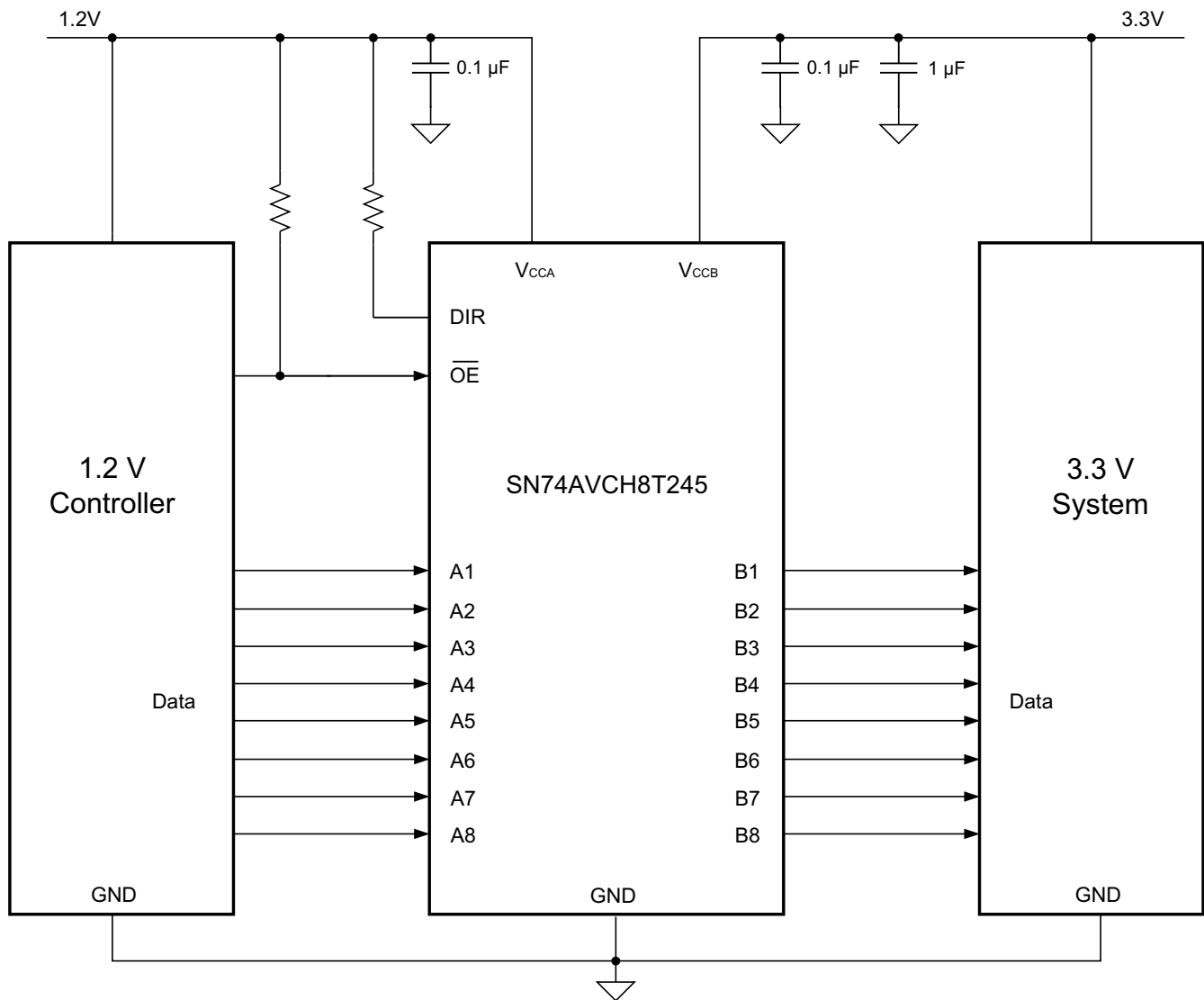


図 8-1. Typical Application Schematic

8.2.1 Design Requirements

For this design example, use the parameters listed in 表 8-1.

表 8-1. Design Parameters

DESIGN PARAMETERS	EXAMPLE VALUE
Input voltage	1.2V to 3.6V
Output voltage	1.2V to 3.6V

8.2.2 Detailed Design Procedure

To begin the design process, determine the following:

- Input voltage range:
 - Use the supply voltage of the device that is driving the SN74AVCH8T245 device to determine the input voltage range. For a valid logic high, the value must exceed the V_{IH} of the input port. For a valid logic low, the value must be less than the V_{IL} of the input port.
- Output voltage range:
 - Use the supply voltage of the device that the SN74AVCH8T245 device is driving to determine the output voltage range.

8.2.3 Application Curves

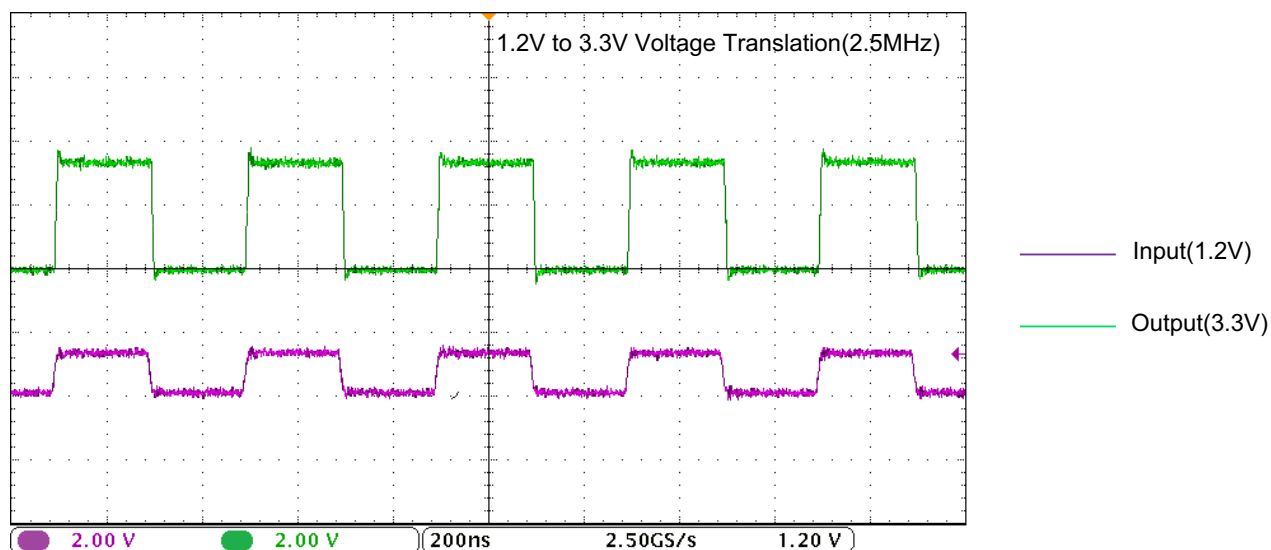


図 8-2. Translation Up (1.2V to 3.3V) at 2.5MHz

8.3 Power Supply Recommendations

The design of the output-enable (\overline{OE}) input circuit is referenced to V_{CCA} so that all outputs are placed in the high-impedance state when the \overline{OE} input is high. To put the outputs in a high-impedance state during power up or power down, the \overline{OE} input pin must be tied to V_{CCA} through a pullup resistor and must not be enabled until V_{CCA} and V_{CCB} are fully ramped and stable. The current-sinking capability of the driver determines the minimum value of the pullup resistor to V_{CCA} .

V_{CCA} or V_{CCB} can be powered up first. If the SN74AVCH8T245 is powered up in a permanently enabled state (for example \overline{OE} is always kept low), then pullup resistors are recommended at the input. Doing this allows for proper, glitch-free, power-up. For more information, see [Designing with SN4LVCXT245 and SN74LVCHXT245 Family of Direction Controlled Voltage Translators/Level-Shifters](#). In addition, the \overline{OE} pin may be shorted to GND if the application does not require use of the high-impedance state at any time.

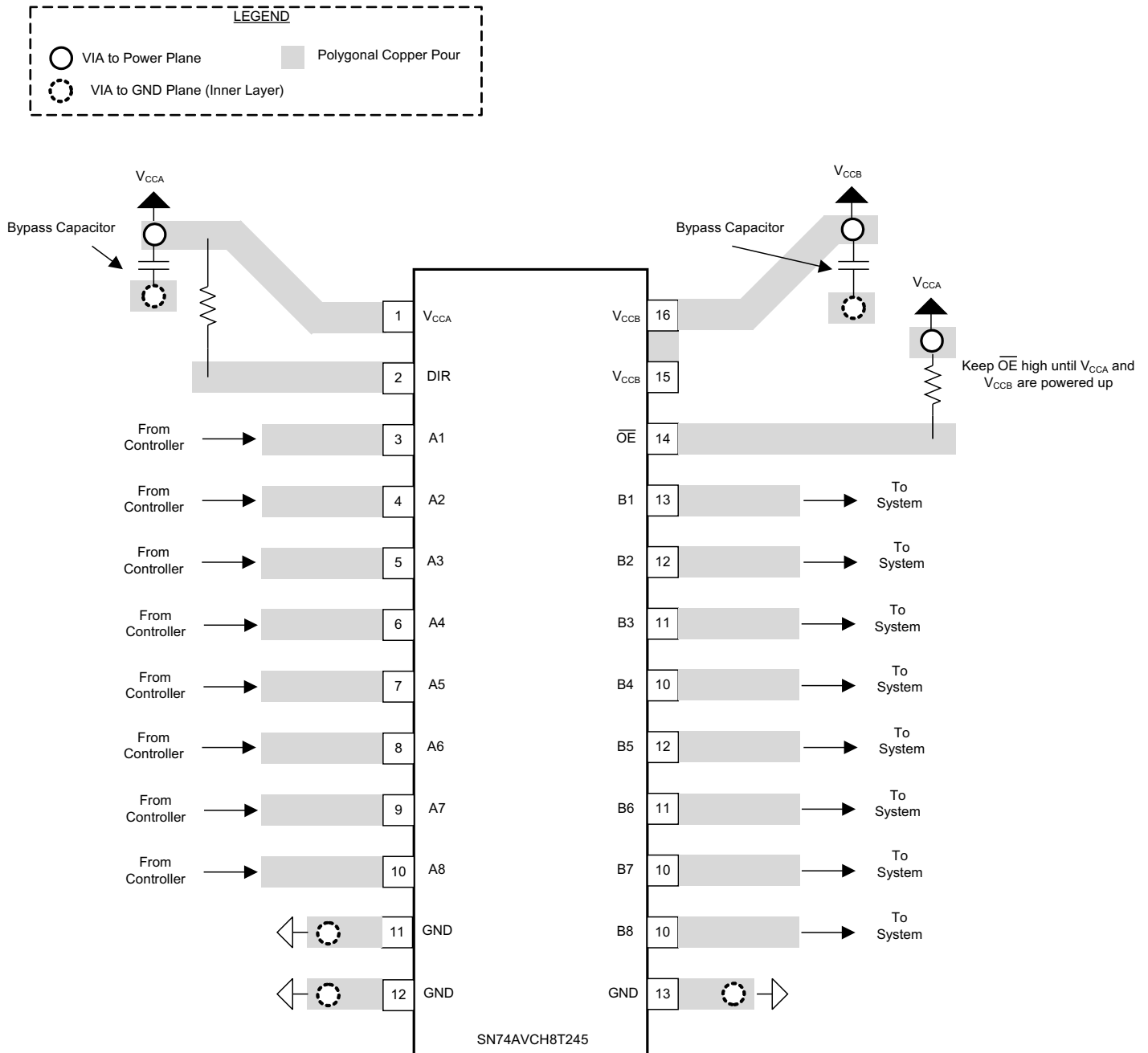
8.4 Layout

8.4.1 Layout Guidelines

For device reliability, TI recommends following the common printed-circuit board layout guidelines.

- Use bypass capacitors on power supplies.
- Use short trace lengths to avoid excessive loading.
- Placing pads on the signal paths for loading capacitors or pullup resistors to help adjust rise and fall times of signals depending on the system requirements.

8.4.2 Layout Example



8-3. SN74AVCH8T245 Layout Example

9 Device and Documentation Support

9.1 Documentation Support

9.1.1 Related Documentation

For related documentation, see the following:

- Texas Instruments, [Designing with SN74LVCXT245 and SN74LVCHXT245 Family of Direction Controlled Voltage Translators/Level-Shifters](#)
- Texas Instruments, [Bus-Hold Circuit](#)
- Texas Instruments, [AVC Logic Family Technology and Applications](#)
- Texas Instruments, [CMOS Power Consumption and Cpd Calculation](#)

9.2 ドキュメントの更新通知を受け取る方法

ドキュメントの更新についての通知を受け取るには、www.tij.co.jp のデバイス製品フォルダを開いてください。[通知] をクリックして登録すると、変更されたすべての製品情報に関するダイジェストを毎週受け取ることができます。変更の詳細については、改訂されたドキュメントに含まれている改訂履歴をご覧ください。

9.3 サポート・リソース

テキサス・インスツルメンツ E2E™ サポート・フォーラムは、エンジニアが検証済みの回答と設計に関するヒントをエキスパートから迅速かつ直接得ることができる場所です。既存の回答を検索したり、独自の質問をしたりすることで、設計に必要な支援を迅速に得ることができます。

リンクされているコンテンツは、各寄稿者により「現状のまま」提供されるものです。これらはテキサス・インスツルメンツの仕様を構成するものではなく、必ずしもテキサス・インスツルメンツの見解を反映したものではありません。テキサス・インスツルメンツの[使用条件](#)を参照してください。

9.4 Trademarks

テキサス・インスツルメンツ E2E™ is a trademark of Texas Instruments.

すべての商標は、それぞれの所有者に帰属します。

9.5 静電気放電に関する注意事項



この IC は、ESD によって破損する可能性があります。テキサス・インスツルメンツは、IC を取り扱う際には常に適切な注意を払うことを推奨します。正しい取り扱いおよび設置手順に従わない場合、デバイスを破損するおそれがあります。

ESD による破損は、わずかな性能低下からデバイスの完全な故障まで多岐にわたります。精密な IC の場合、パラメータがわずかに変化するだけで公表されている仕様から外れる可能性があるため、破損が発生しやすくなっています。

9.6 用語集

[テキサス・インスツルメンツ用語集](#) この用語集には、用語や略語の一覧および定義が記載されています。

10 Revision History

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

Changes from Revision I (November 2023) to Revision J (April 2024) Page

- Changed kW to kΩ in the *Load Circuit and Voltage Waveforms* figure..... 16

Changes from Revision H (January 2016) to Revision I (November 2023) Page

- ドキュメント全体にわたって表、図、相互参照の採番方法を更新..... 1
- パッケージリード サイズを含めるよう「パッケージ情報」表を更新..... 1
- Updated the *Thermal Information* table for the *DGV*, *PW*, and *RHL* packages..... 6

Changes from Revision G (March 2007) to Revision H (January 2016)

Page

• 「ESD 定格」表、「機能説明」セクション、「デバイスの機能モード」セクション、「アプリケーションと実装」セクション、「電源に関する推奨事項」セクション、「レイアウト」セクション、「デバイスおよびドキュメントのサポート」セクション、「メカニカル、パッケージ、および注文情報」セクションを追加。.....	1
• 「注文情報」表を削除.....	1

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

重要なお知らせと免責事項

テキサス・インスツルメンツは、技術データと信頼性データ(データシートを含みます)、設計リソース(リファレンス デザインを含みます)、アプリケーションや設計に関する各種アドバイス、Web ツール、安全性情報、その他のリソースを、欠陥が存在する可能性のある「現状のまま」提供しており、商品性および特定目的に対する適合性の黙示保証、第三者の知的財産権の非侵害保証を含むいかなる保証も、明示的または黙示的にかかわらず拒否します。

これらのリソースは、テキサス・インスツルメンツ製品を使用する設計の経験を積んだ開発者への提供を意図したものです。(1) お客様のアプリケーションに適した テキサス・インスツルメンツ製品の選定、(2) お客様のアプリケーションの設計、検証、試験、(3) お客様のアプリケーションに該当する各種規格や、その他のあらゆる安全性、セキュリティ、規制、または他の要件への確実な適合に関する責任を、お客様のみが単独で負うものとします。

上記の各種リソースは、予告なく変更される可能性があります。これらのリソースは、リソースで説明されている テキサス・インスツルメンツ製品を使用するアプリケーションの開発の目的でのみ、テキサス・インスツルメンツはその使用をお客様に許諾します。これらのリソースに関して、他の目的で複製することや掲載することは禁止されています。テキサス・インスツルメンツや第三者の知的財産権のライセンスが付与されている訳ではありません。お客様は、これらのリソースを自身で使用した結果発生するあらゆる申し立て、損害、費用、損失、責任について、テキサス・インスツルメンツおよびその代理人を完全に補償するものとし、テキサス・インスツルメンツは一切の責任を拒否します。

テキサス・インスツルメンツの製品は、[テキサス・インスツルメンツの販売条件](#)、または [ti.com](https://www.ti.com) やかかる テキサス・インスツルメンツ製品の関連資料などのいずれかを通じて提供する適用可能な条項の下で提供されています。テキサス・インスツルメンツがこれらのリソースを提供することは、適用されるテキサス・インスツルメンツの保証または他の保証の放棄の拡大や変更を意味するものではありません。

お客様がいかなる追加条項または代替条項を提案した場合でも、テキサス・インスツルメンツはそれらに異議を唱え、拒否します。

郵送先住所: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2024, Texas Instruments Incorporated

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
74AVCH8T245PWRG4	ACTIVE	TSSOP	PW	24	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	WP245	Samples
74AVCH8T245RHLRG4	ACTIVE	VQFN	RHL	24	1000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	WP245	Samples
SN74AVCH8T245DGVR	ACTIVE	TVSOP	DGV	24	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	WP245	Samples
SN74AVCH8T245PW	ACTIVE	TSSOP	PW	24	60	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	WP245	Samples
SN74AVCH8T245PWG4	ACTIVE	TSSOP	PW	24	60	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	WP245	Samples
SN74AVCH8T245PWR	ACTIVE	TSSOP	PW	24	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	WP245	Samples
SN74AVCH8T245RHLR	ACTIVE	VQFN	RHL	24	1000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	WP245	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AVCH8T245DGVR	TVSOP	DGV	24	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74AVCH8T245PWR	TSSOP	PW	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1
SN74AVCH8T245RHLR	VQFN	RHL	24	1000	180.0	12.4	3.8	5.8	1.2	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

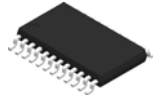
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AVCH8T245DGVR	TVSOP	DGV	24	2000	356.0	356.0	35.0
SN74AVCH8T245PWR	TSSOP	PW	24	2000	356.0	356.0	35.0
SN74AVCH8T245RHLR	VQFN	RHL	24	1000	210.0	185.0	35.0

TUBE


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN74AVCH8T245PW	PW	TSSOP	24	60	530	10.2	3600	3.5
SN74AVCH8T245PWG4	PW	TSSOP	24	60	530	10.2	3600	3.5

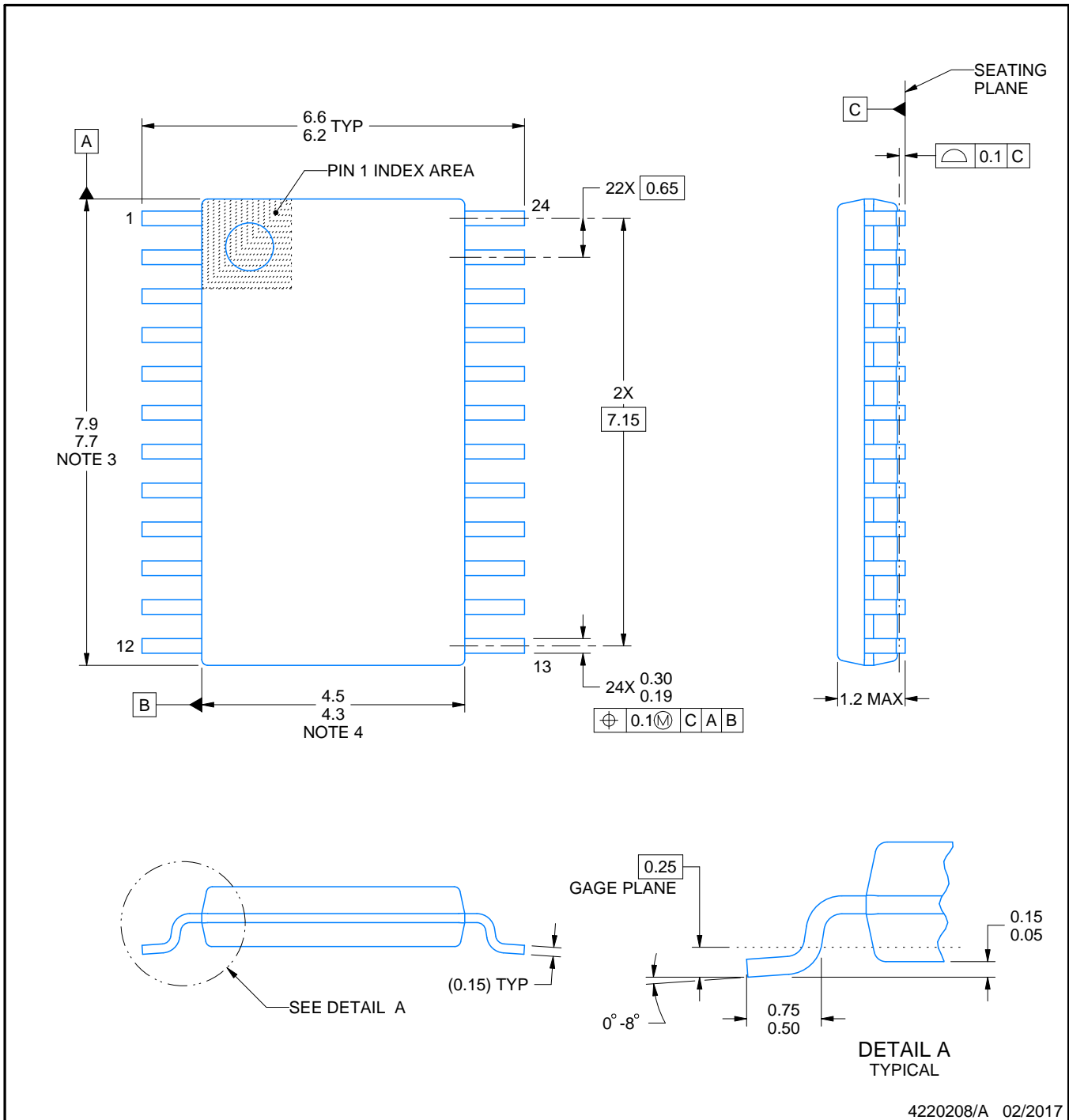
PW0024A



PACKAGE OUTLINE

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



4220208/A 02/2017

NOTES:

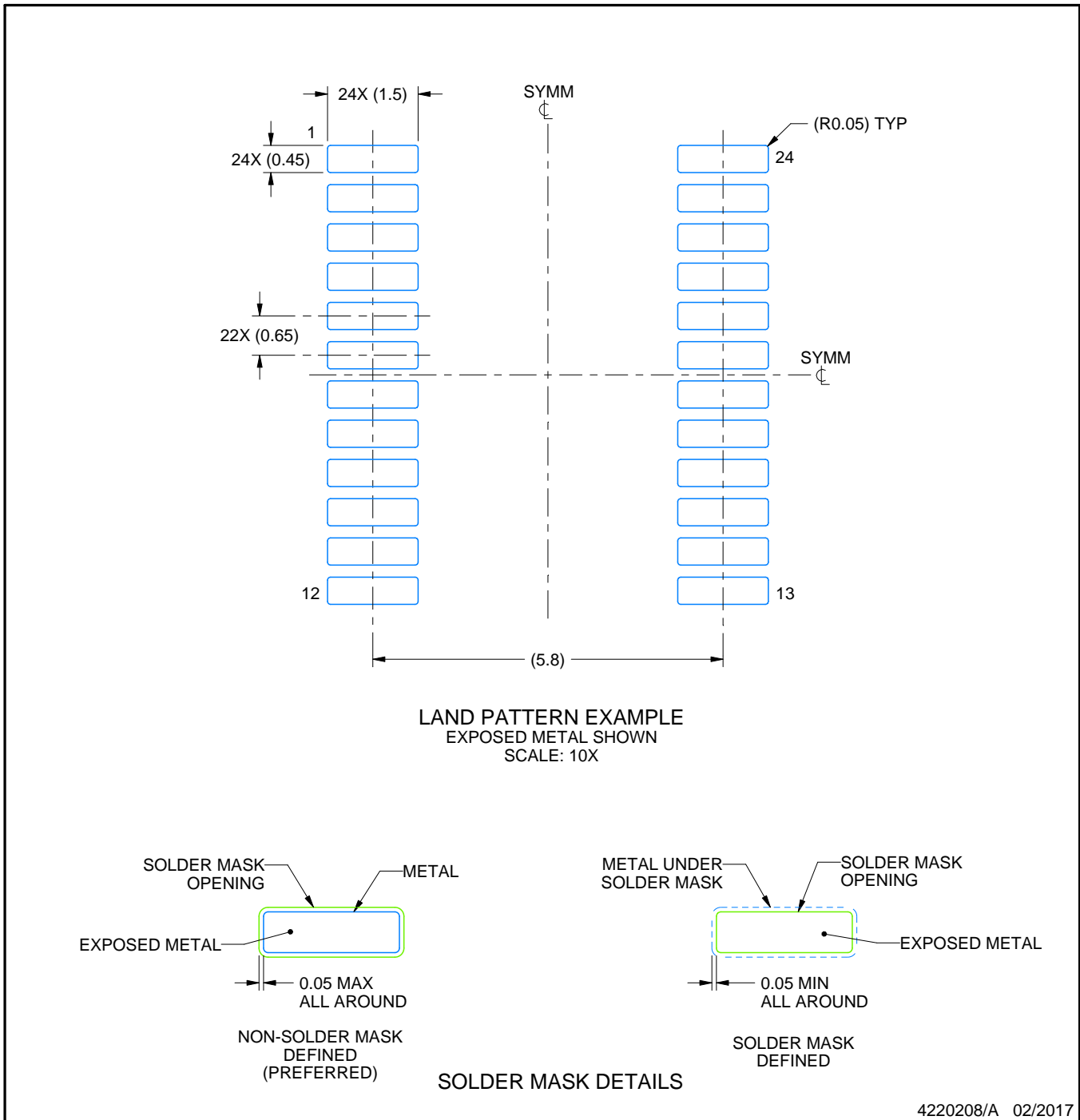
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

PW0024A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES: (continued)

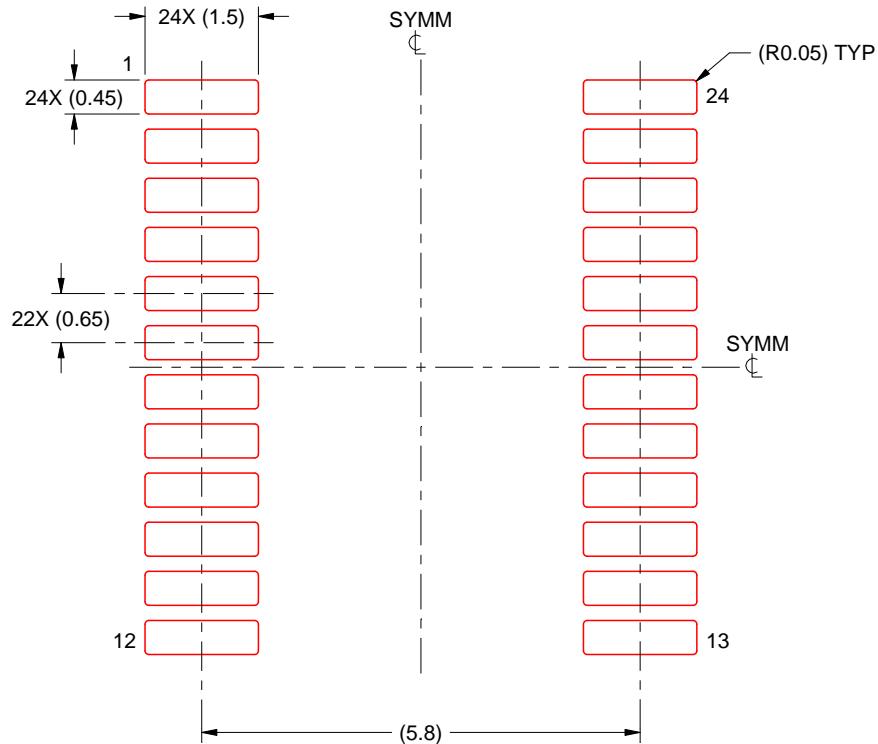
- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0024A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

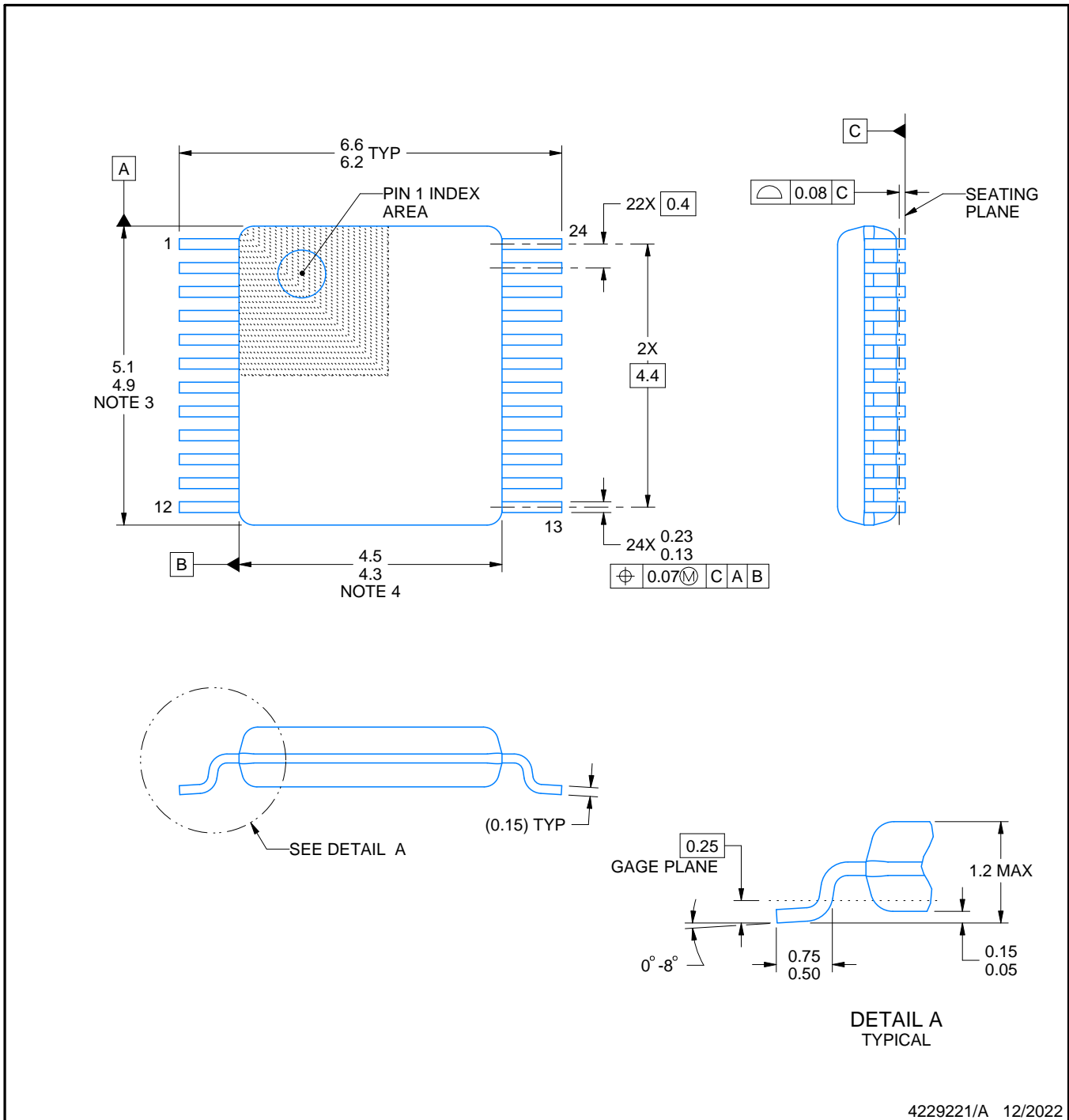
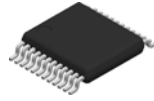


SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220208/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.



4229221/A 12/2022

NOTES:

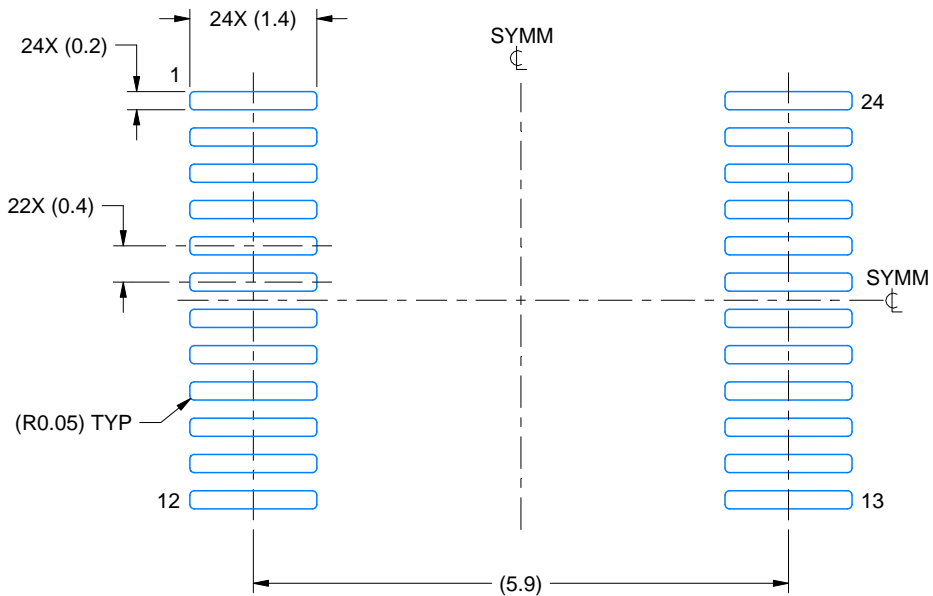
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

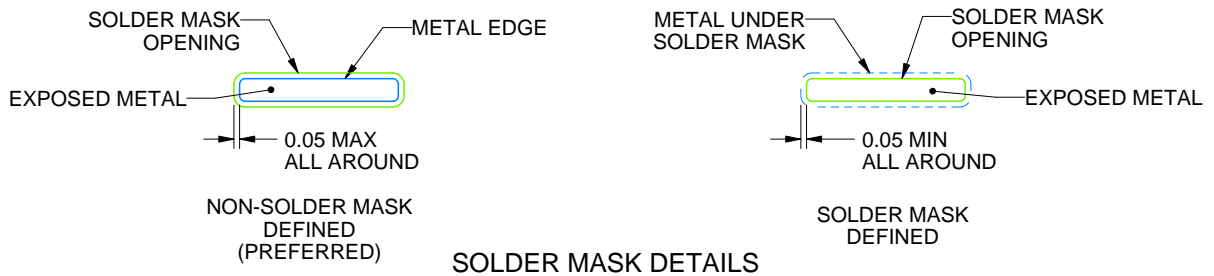
DGV0024A

TVSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 12X



SOLDER MASK DETAILS

4229221/A 12/2022

NOTES: (continued)

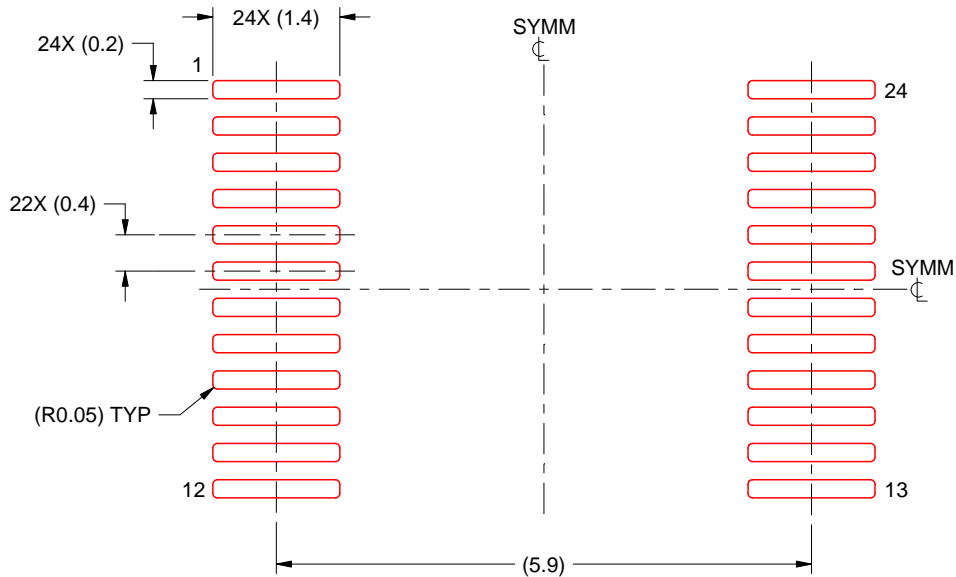
- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DGV0024A

TVSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 12X

4229221/A 12/2022

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

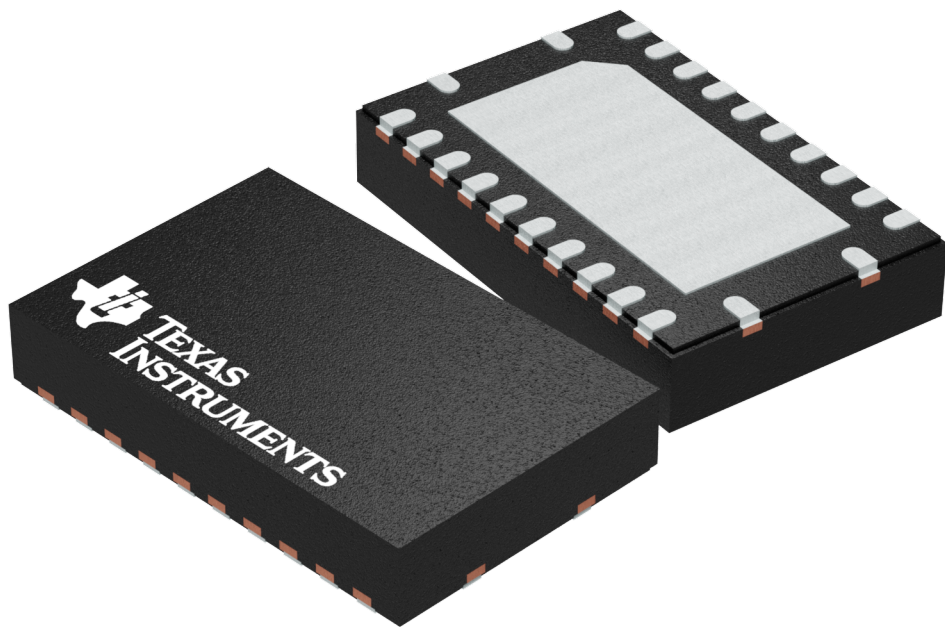
GENERIC PACKAGE VIEW

RGY 24

VQFN - 1 mm max height

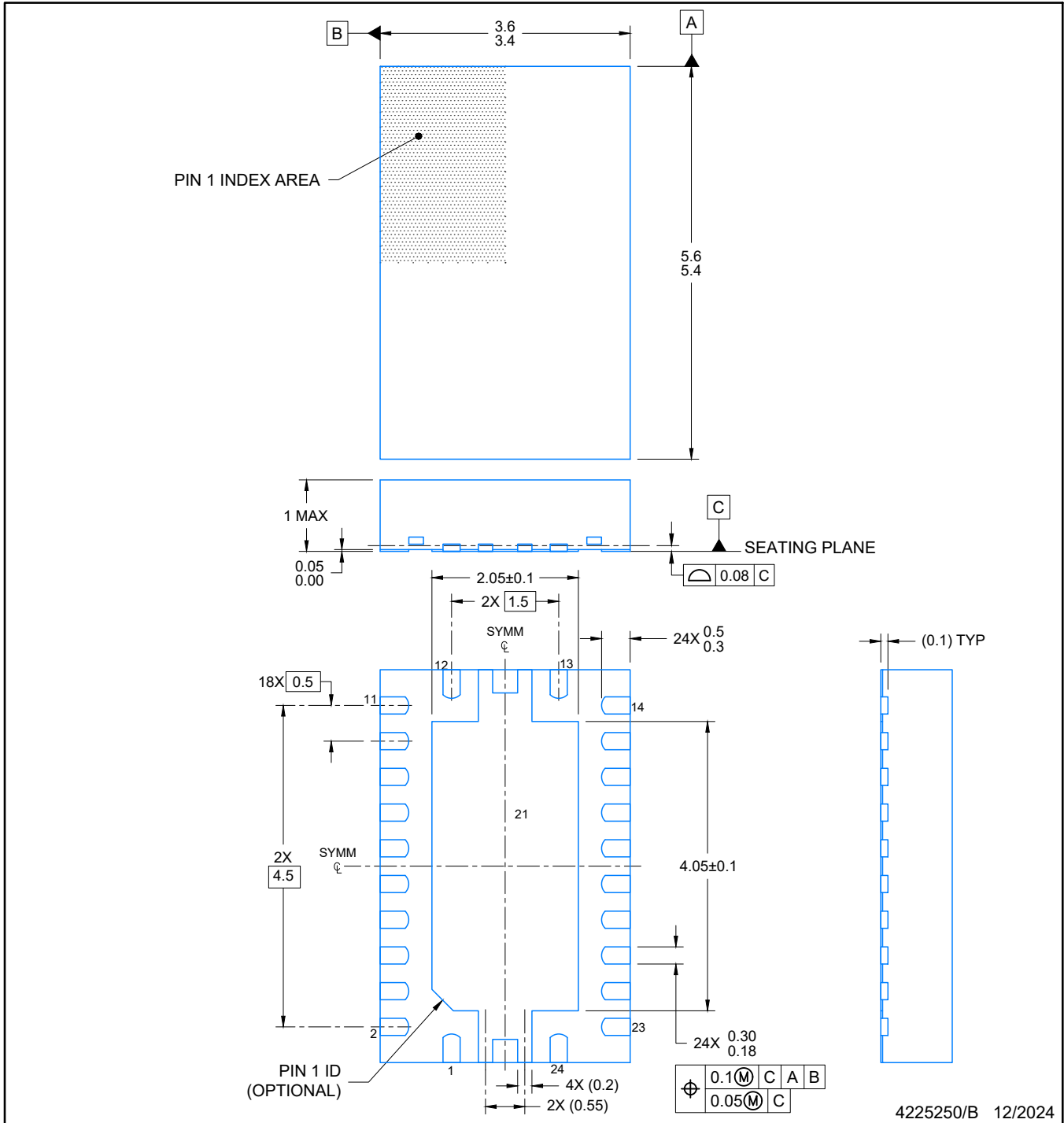
5.5 x 3.5 mm, 0.5 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

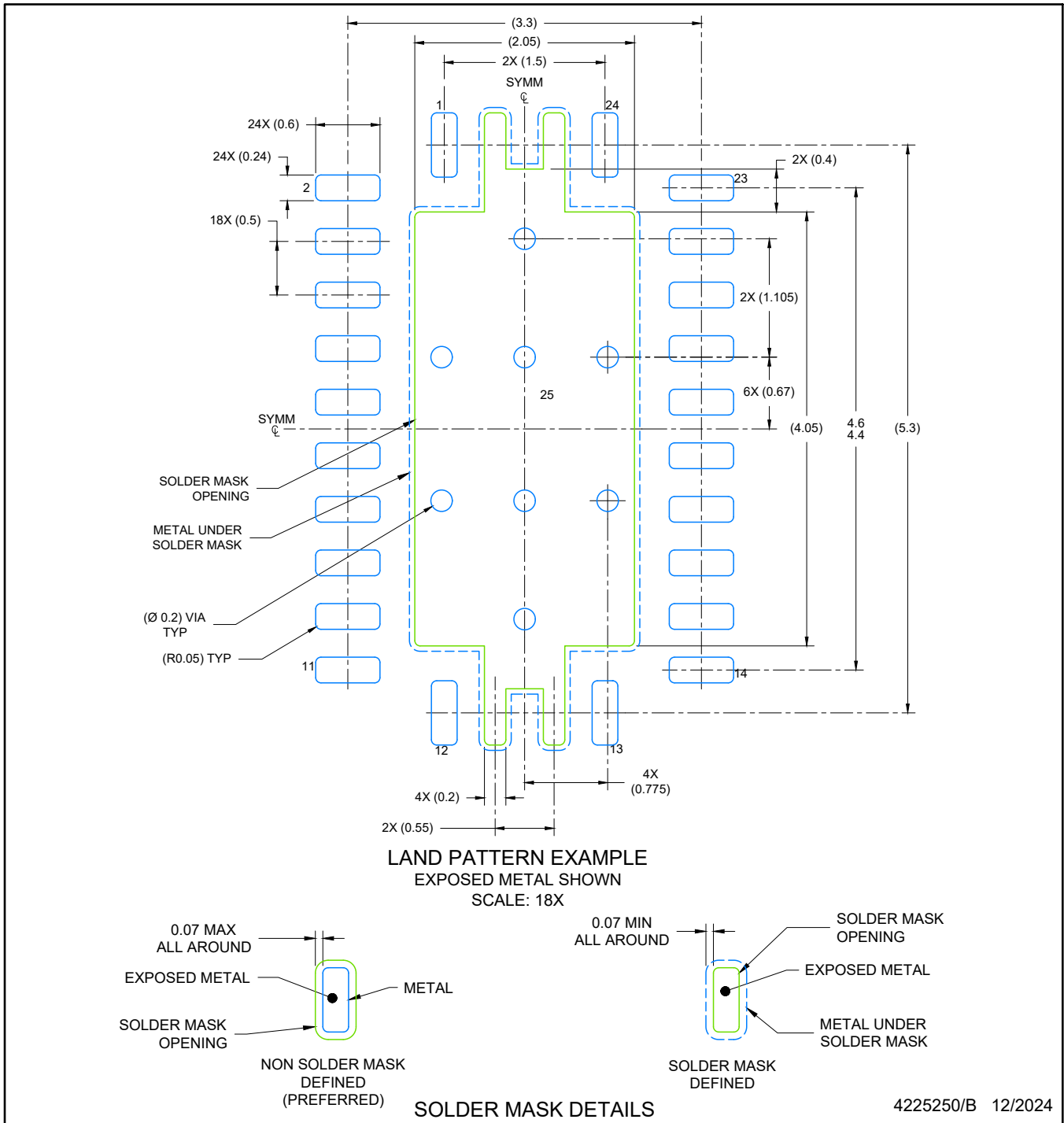
4203539-5/J



4225250/B 12/2024

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for optimal thermal and mechanical performance.



NOTES: (continued)

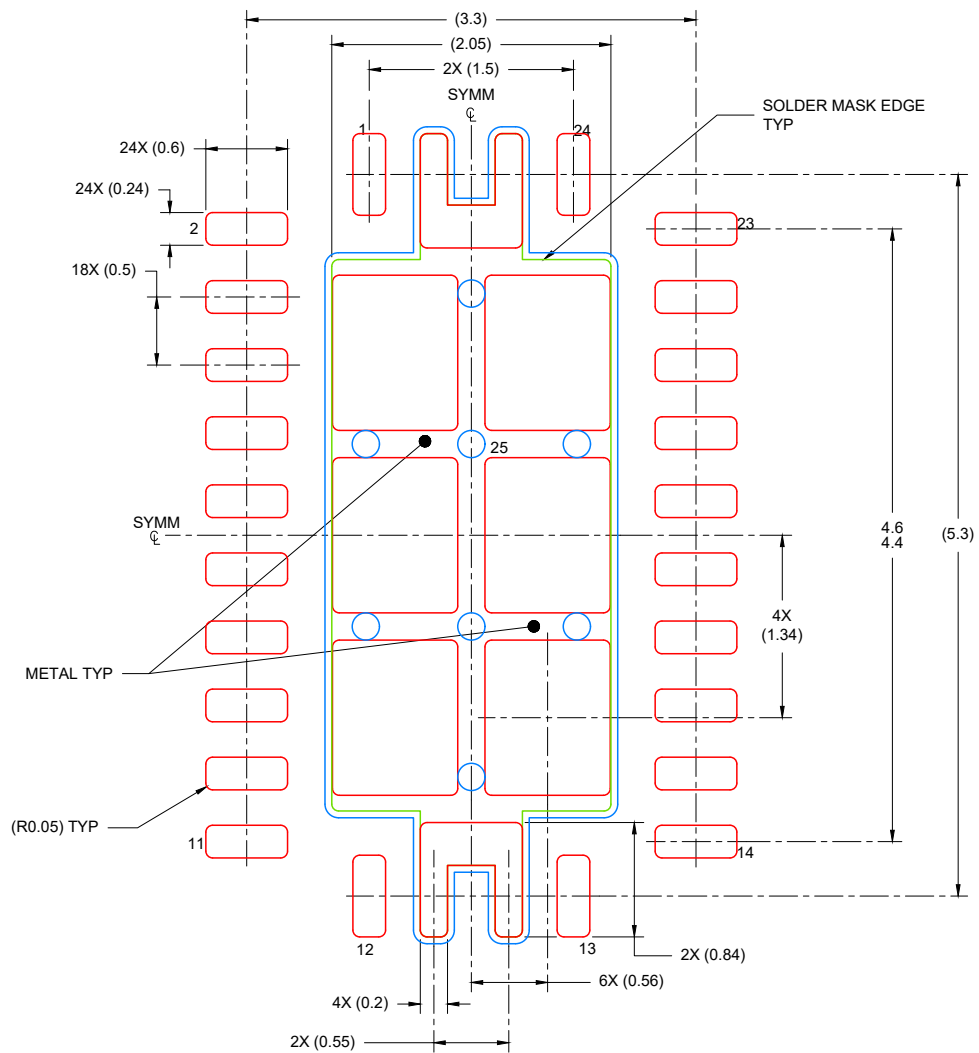
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/sluea271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

VQFN - 1 mm max height

RHL0024A

PLASTIC QUAD FLATPACK- NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD
80% PRINTED COVERAGE BY AREA
SCALE: 18X

4225250/B 12/2024

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

重要なお知らせと免責事項

テキサス・インスツルメンツは、技術データと信頼性データ(データシートを含みます)、設計リソース(リファレンス デザインを含みます)、アプリケーションや設計に関する各種アドバイス、Web ツール、安全性情報、その他のリソースを、欠陥が存在する可能性のある「現状のまま」提供しており、商品性および特定目的に対する適合性の黙示保証、第三者の知的財産権の非侵害保証を含むいかなる保証も、明示的または黙示的にかかわらず拒否します。

これらのリソースは、テキサス・インスツルメンツ製品を使用する設計の経験を積んだ開発者への提供を意図したものです。(1) お客様のアプリケーションに適したテキサス・インスツルメンツ製品の選定、(2) お客様のアプリケーションの設計、検証、試験、(3) お客様のアプリケーションに該当する各種規格や、その他のあらゆる安全性、セキュリティ、規制、または他の要件への確実な適合に関する責任を、お客様のみが単独で負うものとし、ます。

上記の各種リソースは、予告なく変更される可能性があります。これらのリソースは、リソースで説明されているテキサス・インスツルメンツ製品を使用するアプリケーションの開発の目的でのみ、テキサス・インスツルメンツはその使用をお客様に許諾します。これらのリソースに関して、他の目的で複製することや掲載することは禁止されています。テキサス・インスツルメンツや第三者の知的財産権のライセンスが付与されている訳ではありません。お客様は、これらのリソースを自身で使用した結果発生するあらゆる申し立て、損害、費用、損失、責任について、テキサス・インスツルメンツおよびその代理人を完全に補償するものとし、テキサス・インスツルメンツは一切の責任を拒否します。

テキサス・インスツルメンツの製品は、[テキサス・インスツルメンツの販売条件](#)、または [ti.com](https://www.ti.com) やかかるテキサス・インスツルメンツ製品の関連資料などのいずれかを通じて提供する適用可能な条項の下で提供されています。テキサス・インスツルメンツがこれらのリソースを提供することは、適用されるテキサス・インスツルメンツの保証または他の保証の放棄の拡大や変更を意味するものではありません。

お客様がいかなる追加条項または代替条項を提案した場合でも、テキサス・インスツルメンツはそれらに異議を唱え、拒否します。

郵送先住所：Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2025, Texas Instruments Incorporated